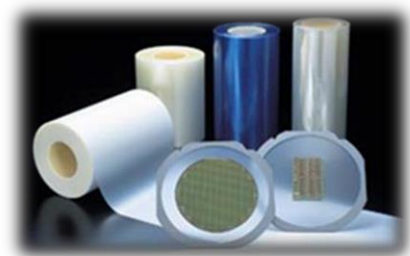
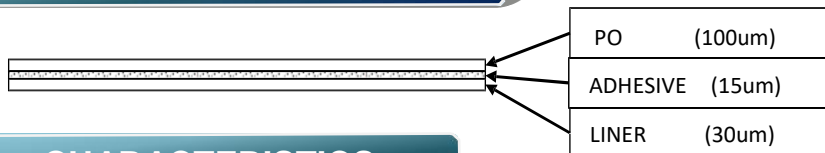


Wafer Dicing Tape (UV series) EM100

DESCRIPTION

High technology is required to a dicing tape with the developments of diversified chips with high quality, in accordance with requirements of each type of wafer. dicing tapes produced by DS are widely used for dicing and singulation of driver ICs, LTCC substrates, EMC package substrates, Si wafers, ceramics, glass, lenses and so on.

STRUCTURE



CHARACTERISTICS

Item		Unit	Value
Width		mm	300
Length		M	100
Thickness	Liner Thickness	μ m	30± 3
	Adhesive Thickness	μ m	15± 2
	PO Thickness	μ m	100± 3
	Total Thickness	μ m	145± 8
Adhesion	Adhesion	g/25 mm	1,300± 200
	Adhesion after UV.	g/25 mm	35± 15

UV exposure : 460 mJ/cm²

ADVANTAGE

- Excellent control to back-side chipping and chip fly-off.
- Excellent adhesiveness.
- Smooth peeling by UV.
- High performance to EMC (Epoxy Mold Compound) and other types of difficult-to-adhere workpiece.
- Easy to release for next process
- Produce in 1000 class clean room